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(54) **SEMICONDUCTOR DEVICE**

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(57) Abstract:

PURPOSE: To contrive the improvement of testability to a large scale semiconductor device by a method wherein each pad part is divided (to electrically isolate) into two of a pad on one side and a pad on the other side.

CONSTITUTION: Each Al pad part 9 is arranged in close contact to other Al pad parts 9 and is divided into two of an Al pad 9a and an Al pad 9b, both of which are electrically isolated. The Al pad 9a and the Al pad 9b of each Al pad part 9 are not electrically connected, but the necessary wiring is performed on the Al pads 9a and 9b through Al wirings 10 excluding the parts between both Al pads 9a and 9b. As each Al pad part 9 is divided into the Al pad 9a and the Al pad 9b and is provided in such a way, an inspection (inspection of the characteristics) of each unit 6 or 7 itself and an inspection of a wiring network 8 can be carried out accurately and easily by an automatic tester without being subjected to the effect of the other units erecting a probe on each of the Al pad 9a and the Al pad 9b, both of which constituted each Al pad 9.

